

customer	
pcb name	
WE article number	
engineer	
date	



Multilayer 4 Layers

PCB Thickness : 1,66 mm +/- 10%

Rigid area Structure	Rigid area Thickness	Material description	Viatypes	Layer usage	Impedance	
					Er	Z[Ohm] Line / Space
Soldermask	15					
L1	45	* Incl. Plating	Top-Layer		3,5	
	380	FR4 TG 135			4,5	
L2	35					
	710	FR4 TG 135			4,7	
L3	35					
	380	FR4 TG 135			4,5	
L4	45	* Incl. Plating	Bottom-Layer			
Soldermask	15				3,5	

Notes:
50 % copper occupancy IL
final copper thickness according to IPC 6012
Dielectric material according IPC-4101 E / 24
For Microvia technology please use our HDI stackups
Revision: Created: W. Brylka / Scrutinised: A. Schilpp / Approved: A.Schilpp
Template Revision: 06/2018 by Andreas Schilpp

Via types - Standard and options		
Standard Via	Plugged Via (Type III-a)	Filled & Capped Via (IPC Type VII)